

**AMENDMENT TO SPECIFICATION**

Please rewrite paragraph 18 as follows:

[018] A connector 213 may be provided along with the control circuit for battery connection. A dissipation heat sink 214 with ~~geographic~~ geometric features to dissipate heat, such as fins, grooves, wings, holes or other physical features may be used. Thus, the semiconductor light source may be affixed to or in heat conductance with a secondary heat sink. The secondary heat sink in turn may be attached to or in heat conductance with a dissipation heat sink. This establishes a heat conductance path from the semiconductor light source to the secondary heat sink to the dissipation heat sink where heat is dissipated. Avoidance of heat buildup is important to avoid overheating the semiconductor light source and decreasing its light intensity output or decreasing its life. If desired, a semiconductor light source may be directly mounted to the dissipation heat sink. The dissipation heat sink may omit geographic features if desired. A clip 215 can be used to attach the heat sink 214 to a mining helmet.